

PATENT

1763

Case Docket No. ASMJP.100AUS

Date: December 4, 2002

Page 1

In re application of : Kiyoshi Satoh, et al.
App. No. : 09/982,454
Filed : October 17, 2001
For : SEMICONDUCTOR
SUBSTRATE-SUPPORTING
APPARATUS
Examiner : A. Crowell
Art Unit : 1763

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(Date)

Katsuhiro Arai, Reg. No. 43,315

UNITED STATES PATENT AND TRADEMARK OFFICE
P.O. Box 2327
Arlington, VA 22202

Sir:

Transmitted herewith is an amendment in the above-identified application.


The fee has been calculated as shown below:

CLAIMS AS FILED						
	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDITIONAL FEE
Total Claims	14	—	20	= 0 ×	\$18	= \$0
Independent Claims	2	—	3	= 0 ×	\$84	= \$0
Information Disclosure Statement filing fee						\$180
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT						\$180

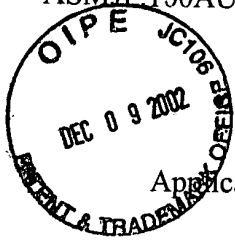
- (X) Amendment in eleven (11) pages
- (X) Information Disclosure Statement; PTO-1449 with three (3) references.
- (X) English translation of the Priority Document.
- (X) A copy of the Response for a Request Substitute Papers filed by the facsimile on October 17, 2001 in thirty (30) pages.
- (X) Return prepaid postcard.
- (X) A check in the amount of \$180.00 is enclosed.

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Satoh et al.) Group Art Unit 1763
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 Examiner : A. Crowell)

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AMENDMENT

Assistant Commissioner for Patents
 Washington, D.C. 20231

Dear Sir:

In response to the Office Action mailed September 5, 2002 (Paper number 6), please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel Claims 6, 8, and 17-20.

Please amend Claims 1, 4, 7, 10, and 13 as follows:

1. (Amended) A semiconductor substrate-supporting apparatus for supporting and heating a single semiconductor substrate inside a vacuum-pumped reaction chamber, comprising:
- a substrate-supporting surface having a concave portion including a depression slanting toward the center of the substrate-supporting surface, wherein only a peripheral portion of the back surface of the substrate, when loaded, contacts the slanting surface of the concave portion;
 - a surface peripheral portion formed around the substrate-supporting surface, said surface peripheral portion having a lip portion which protrudes in a ring shape, said lip portion having a top surface and a slanted inner side surface to prevent a plasma from